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PTN36241G

SuperSpeed USB 3.0 redriver

Rev. 1 — 9 September 2015

Product short data sheet

1. General description

PTN36241G is a very small, low power SuperSpeed USB 3.0 redriver IC that enhances signal quality by performing receive equalization on the deteriorated input signal followed by transmit de-emphasis maximizing system link performance for mobile applications. With its superior differential signal conditioning and enhancement capability, the device delivers significant flexibility and performance scaling for various systems with different PCB trace and cable channel conditions and still benefit from optimum power consumption.

PTN36241G is a dual-channel device that supports data signaling rate of 5 Gbit/s through each channel. The data flow of one channel is facing the USB host, and another channel is facing the USB peripheral or device. Each channel consists of a high-speed Transmit (Tx) differential lane and a high-speed Receive (Rx) differential lane.

PTN36241G has built-in advanced power management capability that enables significant power savings under various different USB 3.0 Low-power modes (U2/U3). It can detect link electrical conditions and can dynamically activate/de-activate internal circuitry and logic. The device performs these actions without host software intervention and conserves power.

PTN36241G is powered from a 1.8 V supply and is available in a small X2QFN12 package (1.25 mm × 2.1 mm × 0.35 mm) with 0.4 mm pitch.

2. Features and benefits

- Supports USB 3.0 specification (SuperSpeed only)
- Compliant to SuperSpeed USB 3.0 standard
- Support of two channels
- Pin out data flow matches USB 3.0 Micro-AB/Micro-B receptacle pin assignments
- Two control pins to select optimized signal conditions
 - ◆ Receive equalization on each channel to recover from InterSymbol Interference (ISI) and high-frequency losses, with provision to choose equalization gain settings per channel
 - ◆ Transmit de-emphasis on each channel delivers pre-compensation suited to channel conditions
 - ◆ Output swing adjustment
- Integrated termination resistors provide impedance matching on both transmit and receive sides
- Automatic receiver termination detection
- Low active power: 189 mW/105 mA (typical) for $V_{DD} = 1.8\text{ V}$



- Power-saving states:
 - ◆ 1.8 mW/1 mA (typical) when in U2/U3 states
 - ◆ 0.9 mW/0.5 mA (typical) when no connection detected
 - ◆ 3.6 μ W/2 μ A (typical) when in Deep power-saving state
- Excellent differential and common return loss performance
 - ◆ 14 dB differential and 15 dB common-mode return loss for 10 MHz to 1250 MHz
- Flow-through pinout to ease PCB layout and minimize crosstalk effects
- Hot Plug capable
- Power supply: $V_{DD} = 1.8$ V (typical)
- Compliant with JESD 78 Class II
- Very thin X2QFN12 package: 1.25 mm \times 2.1 mm \times 0.35 mm, 0.4 mm pitch
- ESD protection exceeds 7000 V HBM per JDS-001-2012 and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- Operating temperature range: -40 °C to 85 °C

3. Applications

- Smart phones, tablets
- Active cables
- Notebook/netbook/nettop platforms
- Docking stations and AIO platforms
- USB 3.0 peripherals such as flat panel display, consumer/storage devices, printers or USB 3.0 capable hubs/repeaters

4. System context diagrams

[Figure 1](#) illustrates PTN36241G usage.

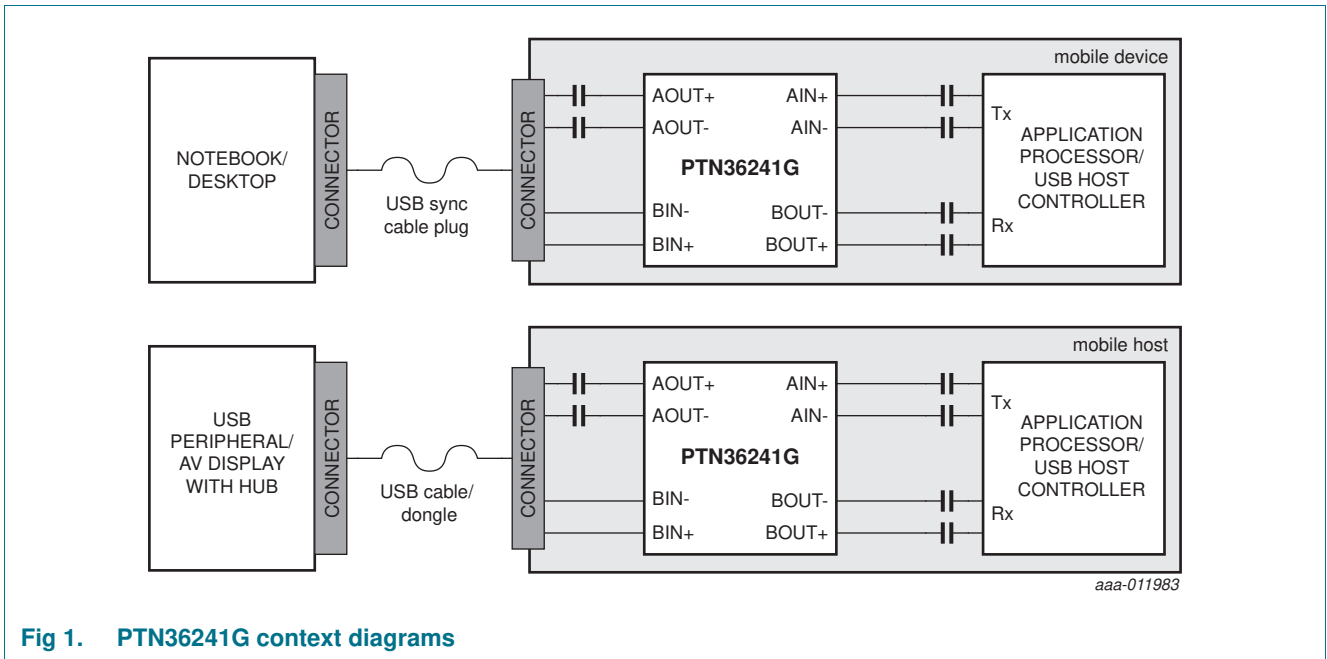


Fig 1. PTN36241G context diagrams

5. Ordering information

Table 1. Ordering information

Type number	Topside marking	Package		Version
		Name	Description	
PTN36241G	41G	X2QFN12	plastic, super thin quad flat package; no leads; 12 terminals; body 1.25 × 2.10 × 0.35 mm; 0.4 mm lead pitch	SOT1408-1

5.1 Ordering options

Table 2. Ordering options

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature
PTN36241G	PTN36241GHXAZ	X2QFN12	Reel 7" Q1/T1 *Standard mark	500	T _{amb} = -40 °C to +85 °C
PTN36241G	PTN36241GHXZ	X2QFN12	Reel 7" Q1/T1 *Standard mark	6000	T _{amb} = -40 °C to +85 °C

6. Block diagram

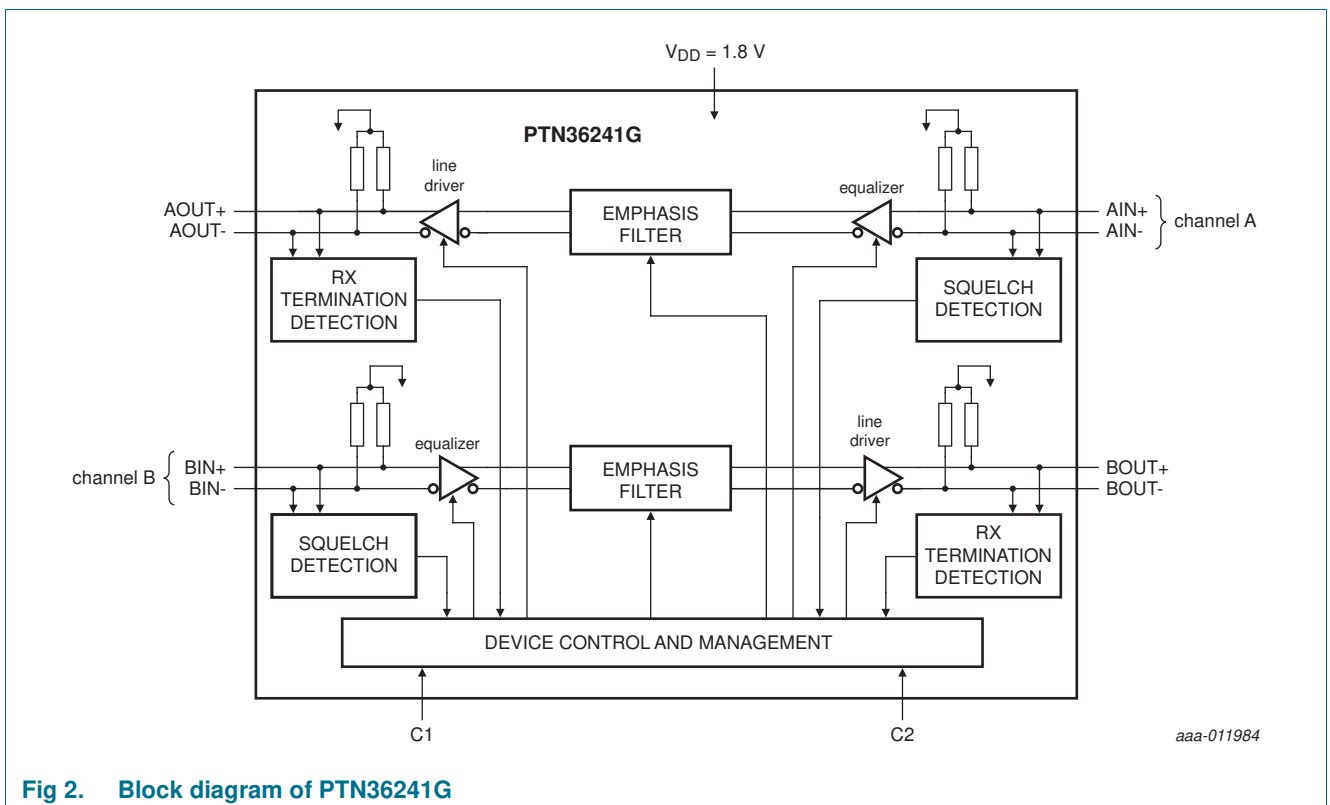


Fig 2. Block diagram of PTN36241G

7. Revision history

Table 3. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PTN36241G_SDS v.1	20150909	Product short data sheet	-	-

8. Legal information

8.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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